

### ***Claim Listing***

1. (currently amended) A multiple layer inductor implemented on a substrate having a plurality of layers, each layer having a top surface and a bottom surface, said multiple layer inductor comprising:

a first spiral conductive pattern disposed on a top surface of a first of the plurality of layers;

a second spiral conductive pattern disposed on a top surface of a second of the plurality of layers;

a continuing interconnection coupled to said first and second spiral conductive patterns;

an interface having a first terminal and a second terminal disposed on said top surface of said first of the plurality of layers, wherein said first terminal is coupled to said first spiral conductive patterns and second terminal is coupled to said second spiral conductive pattern;

a first conductive shield pattern having a first common voltage potential and disposed on a top surface of a third of the plurality of layers, wherein said third of the plurality of layers is adjacent to said second of the plurality of layers; and

a second conductive shield pattern having a second common voltage potential and disposed on a top surface of a fourth of the plurality of layers, wherein said fourth of the plurality of layers is adjacent to said top surface of said first of the plurality of layers[.];

first and second conductive side shield patterns disposed on respective perimeters of said first and second layers.

2. (cancelled)

3. (previously presented) The multiple layer inductor of claim 1, wherein said continuing interconnection comprises:

- a first via coupled to said first and second spiral conductive patterns; and
- a second via coupled to said second spiral conductive pattern and said second terminal.

4. (withdrawn) The multiple layer inductor of claim 1, wherein said continuing interconnection comprises:

- a first via coupled to said first spiral conductive pattern;
- a second via coupled to said second spiral conductive pattern;
- a third spiral conductive pattern disposed on a fourth surface that is coupled to said first and second vias.

5. (withdrawn) The multiple layer inductor of claim 4, wherein said first and second spiral conductive patterns have a first orientation, and wherein said third spiral conductive pattern has a second orientation that is different than said first orientation.

6. (withdrawn) The multiple layer inductor of claim 1, wherein said continuing interconnection comprises:

- a first via coupled to said first spiral conductive pattern;

a second via coupled to said second spiral conductive pattern; and  
a plurality of coupled of spiral conductive patterns, each disposed on a  
respective one of a plurality of adjacent layers;  
wherein a first of the plurality of spiral conductive patterns is coupled to  
said first via, and a second of the plurality of spiral conductive patterns is coupled to said  
second via.

7. (withdrawn) The multiple layer inductor of claim 6, wherein said plurality of  
coupled of spiral conductive patterns have orientations that alternate according to  
adjacent surfaces.

8. (original) The multiple layer inductor of claim 1, wherein said first and second  
spiral conductive patterns have different orientations.

9. (canceled)

10. (original) The multiple layer inductor of claim 9, wherein said first and  
second shield patterns are grounded.

11. (withdrawn) The multiple layer inductor of claim 1, further comprising first  
and second conductive side shield patterns disposed on said first and second layers,  
respectively.

12. (withdrawn) The multiple layer inductor of claim 11, wherein said first and second side shield patterns are grounded.

13. (withdrawn) A method of designing a multiple layer spiral inductor having a plurality of spiral conductive patterns disposed on corresponding substrate surfaces, the method comprising:

- (a) determining a number of spiral conductive patterns;
- (b) selecting a spiral shape for each of the spiral conductive patterns;
- (c) defining spatial characteristics for each of the spiral conductive patterns; and
- (d) verifying the performance of the multiple layer spiral inductor having the determined number of spiral conductive patterns, the selected spiral shape, and the defined spatial characteristics.

14. (withdrawn) The method of claim 13, wherein step (c) comprises:

- (1) defining a line width, an outer radius, and a mean radius for each of the spiral conductive patterns.

15. (withdrawn) The method of claim 14, wherein step (c) further comprises:

- (2) defining an inner radius for each of the spiral conductive patterns.

16. (withdrawn) The method of claim 13, wherein step (d) comprises:

- (1) calculating an inductance based on the determined number of spiral conductive patterns, the selected spiral shape, and the defined spatial characteristics; and
- (2) repeating steps (a), (b), and (c) when the calculated inductance is not substantially equal to a target inductance.

17. (withdrawn) The method of claim 16, wherein step (1) comprises

calculating the inductance according to:

$$L = \frac{37.5\mu_0 n^2 a^2}{(22r - 14a)}, \text{ wherein}$$

$L$  is the inductance in Henries,

$n$  is a total number of turns in the plurality of spiral conductive patterns,

$\mu_0$  is the permeability of free space,

$r$  is an outer radius for each of the spiral conductive patterns in meters, and

$a$  is the mean radius for each of the spiral conductive patterns in meters.

18. (withdrawn) The method of claim 13, wherein step (d) further comprises:

- (3) simulating a circuit application of the multiple layer spiral inductor having the determined number of spiral conductive patterns, the selected spiral shape, and the defined spatial characteristics.

19. (withdrawn) A diplexer filter for use in a communications device,  
comprising:  
    one or more multiple layer inductors implemented on a substrate having a  
plurality of surfaces;  
    wherein each of the one or more multiple layer inductors includes:  
    a first spiral conductive pattern disposed on a first of the plurality of  
surfaces;  
    a second spiral conductive pattern disposed on a second of the plurality of  
surfaces;  
    a continuing interconnection coupled to said first and second spiral  
conductive patterns;  
    an interface coupled to said first and second spiral conductive patterns;  
and  
    a first conductive shield pattern disposed on a third of the plurality of  
surfaces, said third surface adjacent to said second surface.

20. (withdrawn) The diplexer filter of claim 19, wherein said communications  
device includes a television tuner.

21. (withdrawn) The diplexer filter of claim 19, wherein said communications  
device is a cable modem.